

DLVR Low Voltage Digital Pressure Sensor Series



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Introduction

The DLVR Series Mini Digital Output Sensor is based on All Sensors' CoBeam²™ Technology. This reduces package stress susceptibility, resulting in improved overall long term stability. The technology also vastly improves position sensitivity compared to single die devices.

The supply voltage options ease integration of the sensors into a wide range of process control and measurement systems, allowing direct connection to serial communications channels. For battery-powered systems, the sensors can enter very low-power modes between readings to minimize load on the power supply.

These calibrated and compensated sensors provide accurate, stable output over a wide temperature range. This series is intended for use with non-corrosive, non-ionic working fluids such as air, dry gases and the like. A protective parylene coating is optionally available for moisture/harsh media protection.

https://www.allsensors.com/products/dlvr-series



For All Sensors Corporation's most recent quality certification documents, please visit www.allsensors.com

DS-0300 / DCN 9086 / Rev G

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DLVR SERIES LOW VOLTAGE DIGITAL PRESSURE SENSORS

Features		Α	pplications		
Pressure Ranges from 0.5 to 60 i	inH2O	 Medical Breathing 			
• 3.3V Supply Voltage Standard /	 Environmental Controls 				
• I2C Standard Interface / SPI Inter	rface Option	• HVAC			
• Better than 1.0% Accuracy Over	• Industrial Con	trols			
Temperature Typical		• Portable / Hand-Held Devices			
Pressure Sensor Maximum F	Ratings	Environn	nental Specifications		
Supply Voltage (Vs)	6 Vdc	Temperature Rang	ges		
Common Mode Pressure	10 psig	Compensated:	Commercial 0°C to 70°C		
Lead Temperature (soldering 2-4 sec.)	270°C	Operating	Industrial -20°C to 85°C -25°C to 85 °C		
Device Temperature	245°C	Storage	-40°C to 125 °C		

Standard Pressure Ranges

Device	Operating	g Range ^A	Proof Pr	essure	Burst Pr	essure	Nominal Span
Device	inH2O	Pa	inH2O	kPa	inH2O	kPa	Counts
DLVR-F50D	± 0.5	125	100	25	300	75	±6,554
DLVR-L01D	± 1	250	100	25	300	75	±6,554
DLVR-L02D	± 2	500	100	25	300	75	±6,554
DLVR-L05D	± 5	1,250	200	50	300	75	±6,554
DLVR-L10D	± 10	2,500	200	50	300	75	±6,554
DLVR-L20D	± 20	5,000	200	50	500	125	±6,554
DLVR-L30D	± 30	7,500	200	50	500	125	±6,554
DLVR-L60D	± 60	15,000	200	50	800	200	±6,554
DLVR-L01G	0 to 1	250	100	25	300	75	13,108
DLVR-L02G	0 to 2	500	100	25	300	75	13,108
DLVR-L05G	0 to 5	1,250	200	50	300	75	13,108
DLVR-L10G	0 to 10	2,500	200	50	300	75	13,108
DLVR-L20G	0 to 20	5,000	200	50	500	125	13,108
DLVR-L30G	0 to 30	7,500	200	50	500	125	13,108
DLVR-L60G	0 to 60	15,000	200	50	800	200	13,108

Note A: Operating range in Pa is expressed as an approximate value.

Humidity Limits (non condensing) 0 to 95% RH

Performance Characteristics for DLVR Series

All parameters are measured at $3.3V \pm 5\%$ or $5.0V \pm 5\%$ (depending on selected voltage option) excitation and 25° C unless otherwise specified. Pressure measurements are with positive pressure applied to PORT B.

Output Span LxxD, FxxD LxxG Offset Output @ Zero Differential Pressure LxxG LxxD, FxxD LxxG Total Error Band F50D L01x, L02x L05x, L10x, L20x, L30x, L60x Span Temperature Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Temperature Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Warm-Up Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Position Sensitivity (±1g) F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x		$\pm 6,554$ 13,108 8,192 1,638 ± 0.60 ± 0.50 ± 0.30 ± 0.50 ± 0.20 ± 0.20 ± 0.20 ± 0.25 ± 0.15	- - - - ±1.5 ±1.0 ±0.75 - - - -	Dec count Dec count Dec count Dec count Count %Span %Span %Span %FSS %FSS %FSS %FSS	1 1 - - 2 2 2 2 3 3 3 3 3 3 4
LxxG Difset Output @ Zero Differential Pressure LxxD, FxxD LxxG Total Error Band F50D D1x, L02x D1x, L02x D5x, L10x, L20x, L30x, L60x Span Temperature Shift F50D, L01x, L02x D5x, L10x, L20x, L30x, L60x Dfset Temperature Shift F50D, L01x, L02x D5x, L10x, L20x, L30x, L60x Dfset Varm-Up Shift F50D, L01x, L02x D5x, L10x, L20x, L30x, L60x Dfset Position Sensitivity (±19) F50D, L01x, L02x	- - - - -	13,108 8,192 1,638 ± 0.60 ± 0.50 ± 0.30 ± 0.20 ± 0.50 ± 0.20 ± 0.20 ± 0.20 ± 0.25 ± 0.15	- - ±1.5 ±1.0 ±0.75	Dec count Dec count Dec count %Span %Span %Span %FSS %FSS %FSS %FSS	1 - - 2 2 2 2 3 3 3 3 3 4
Offset Output @ Zero Differential Pressure LxxD, FxxD LxxG Total Error Band F50D L01x, L02x L05x, L10x, L20x, L30x, L60x Span Temperature Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Temperature Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Warm-Up Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Position Sensitivity (±19) F50D, L01x, L02x	- - - - -	8,192 1,638 ± 0.60 ± 0.50 ± 0.30 ± 0.20 ± 0.50 ± 0.20 ± 0.20 ± 0.20 ± 0.25 ± 0.15	- - ±1.5 ±1.0 ±0.75	Dec count Dec count %Span %Span %Span %FSS %FSS %FSS %FSS %FSS	- - 2 2 2 3 3 3 3 3 4
LxxD, FxxD LxxG Total Error Band F50D L01x, L02x L05x, L10x, L20x, L30x, L60x Span Temperature Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Temperature Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Warm-Up Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Position Sensitivity (±19) F50D, L01x, L02x	- - - -	1,638 ± 0.60 ± 0.50 ± 0.30 ± 0.20 ± 0.20 ± 0.20 ± 0.25 ± 0.15	- ±1.5 ±1.0 ±0.75 - - -	Dec count VSpan VSpan VSpan VSpan VFSS VFSS VFSS VFSS VFSS VFSS VFSS VFS	- 2 2 3 3 3 3 3 4
LxxG Total Error Band F50D L01x, L02x L05x, L10x, L20x, L30x, L60x Span Temperature Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Temperature Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Warm-Up Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Position Sensitivity (±19) F50D, L01x, L02x	- - - -	1,638 ± 0.60 ± 0.50 ± 0.30 ± 0.20 ± 0.20 ± 0.20 ± 0.25 ± 0.15	- ±1.5 ±1.0 ±0.75 - - -	Dec count VSpan VSpan VSpan VSpan VFSS VFSS VFSS VFSS VFSS VFSS VFSS VFS	- 2 2 3 3 3 3 3 4
Total Error Band F50D L01x, L02x L05x, L10x, L20x, L30x, L60x Span Temperature Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Temperature Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Warm-Up Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Position Sensitivity (±19) F50D, L01x, L02x	- - -	± 0.60 ± 0.50 ± 0.30 ± 0.50 ± 0.20 ± 0.20 ± 0.20 ± 0.25 ± 0.15	±1.5 ±1.0 ±0.75 - - - -	%Span %Span %Span %FSS %FSS %FSS %FSS %FSS	2 2 3 3 3 3 3 4
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L01x, L02x L05x, L10x, L20x, L30x, L60x Span Temperature Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Temperature Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Warm-Up Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Position Sensitivity (±19) F50D, L01x, L02x	- - - - - - - - - -	± 0.50 ± 0.30 ± 0.50 ± 0.20 ± 0.50 ± 0.20 ± 0.20 ± 0.25 ± 0.15	±1.0 ±0.75	%Span %Span %FSS %FSS %FSS %FSS %FSS	2 2 3 3 3 3 4
L05x, L10x, L20x, L30x, L60x Span Temperature Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Temperature Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Warm-Up Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Position Sensitivity (±19) F50D, L01x, L02x	· · · · ·	± 0.30 ± 0.50 ± 0.20 ± 0.50 ± 0.20 ± 0.25 ± 0.15	±0.75	%Span %FSS %FSS %FSS %FSS %FSS	2 3 3 3 3 4
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Offset Temperature Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Warm-Up Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Position Sensitivity (±1g) F50D, L01x, L02x	• • • •	±0.50 ±0.20 ±0.25 ±0.15	-	%FSS %FSS %FSS	3 3 4
F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Warm-Up Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Position Sensitivity (±1g) F50D, L01x, L02x		±0.20 ±0.25 ±0.15		%FSS %FSS	3
L05x, L10x, L20x, L30x, L60x Offset Warm-Up Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Position Sensitivity (±1g) F50D, L01x, L02x	• • •	±0.20 ±0.25 ±0.15	-	%FSS %FSS	3
Offset Warm-Up Shift F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Position Sensitivity (±1g) F50D, L01x, L02x		±0.25 ±0.15		%FSS	4
F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Position Sensitivity (±1g) F50D, L01x, L02x		±0.15			
F50D, L01x, L02x L05x, L10x, L20x, L30x, L60x Offset Position Sensitivity (±1g) F50D, L01x, L02x	- -	±0.15	-		
L05x, L10x, L20x, L30x, L60x Offset Position Sensitivity (±1g) F50D, L01x, L02x	-		-	%FSS	
Offset Position Sensitivity (±1g) F50D, L01x, L02x	-	+0.10			4
F50D, L01x, L02x	-	+0.10			
		±0.10	-	%FSS	-
	-	±0.05	-	%FSS	-
Offset Long Term Dfrift (One Year)					
F50D, L01x, L02x	-	±0.25	-	%FSS	-
L05x, L10x, L20x, L30x, L60x	-	±0.15	-	%FSS	-
Linearity, Hysteresis Error					
F50D	-	±0.30	-	%FSS	6
LxxD	-	±0.25	-	%FSS	6
LxxG	-	±0.10	-	%FSS	6
Response Delay					
Sleep - Wake Pressure		0.46	0.53	ms	5, 9
Sleep - Wake All	-	1.10	1.40	ms	5, 9
	6.0 + 1 update period	-	-	ms	5, 9
Update Rate				1115	575
Fast	-	0.50	1.15	ms	5
Noise Reduced	-	1.3	3.1	ms	5
Low Power	-	6.5	9.5	ms	5
Digital Resolution		0.5	5.5	1113	2
Output Resolution	-	14		bit	_
No Missing Codes	- 12	14	-	bit	-
Temperature Output	12	15	-	UIL	-
Resolution	-	11	-	bit	7
Overall Accuracy	-	2	-	°C	7
Current Requirement (3.3V Option)	-	2	-	L	/
Fast		3.5	4.3	mA	5
Noise Reduced	-	3.6	4.5	mA	5
Noise Reduced Low Power	-	3.6 0.72	4.5 0.9		5
	-			mA	5
Sleep (Idle)	-	0.5	5.0	uA	5
Current Requirement (5V Option)		5.0	()		-
Fast	-	5.0	6.0	mA	5
Noise Reduced	-	5.2	6.2	mA	5
Low Power Sleep (Idle)	-	1.1 0.5	1.3 5.0	mA uA	5 5

See following page for performance characteristics table notes



ALL SENSORS

I2C / SPI Electrical Parameters for DLVR Series

Parameter	Symbol	Min	Тур	Max	Units	Notes
Input High Level	-	80	-	100	% of Vs	5
Input Low Level	-	0	-	20	% of Vs	5
Output Low Level	-	-	-	10	% of Vs	5
I2C Pull-up Resistor	-	1000	-	-	Ω	5,8
I2C Load Capacitance on SDA, @ 400 kHz	CSDA	-	-	200	pF	5
I2C Input Capacitance (each pin)	CI2C_IN	-	-	10	pF	5

Pressure Output Transfer Function

	Pressure (inH ₂ O) = 1.25 $\times \left(\frac{Pout_{dig} - OS_{dig}}{2^{14}}\right) \times FSS(inH_2O)$
Where:	
Pout _{dig}	is the sensor 14-bit output
OS _{dig}	is the specified digital offset output (gage = 1,638 and differential = 8,192)
FSS(inH₂O)	is the sensor Full Scale Span in inH2O for Gage Operating Range sensors: Full Scale Pressure for Differential Operaing Range sensors: 2X Full Scale Pressure

Specification Notes

NOTE 1: THE SPAN IS THE ALGEBRAIC DIFFERENCE BETWEEN FULL SCALE DECIMAL COUNTS AND THE OFFSET DECIMAL COUNTS. THE FULL SCALE PRESSURE IS THE MAXIMUM POSITIVE CALIBRATED PRESSURE.

NOTE 2: TOTAL ERROR BAND CONSISTS OF OFFSET AND SPAN TEMPERATURE AND CALIBRATION ERRORS, LINEARITY AND PRESSURE HYSTERESIS ERRORS, OFFSET WARM-UP SHIFT, OFFSET POSITION SENSITIVITY AND LONG TERM OFFSET DRIFT ERRORS.

NOTE 3: SHIFT IS RELATIVE TO 25C.

NOTE 4: SHIFT IS WITHIN THE FIRST HOUR OF EXCITATION APPLIED TO THE DEVICE.

NOTE 5: PARAMETER IS CHARACTERIZED AND NOT 100% TESTED.

NOTE 6: MEASURED AT ONE-HALF FULL SCALE RATED PRESSURE USING BEST STRAIGHT LINE CURVE FIT.

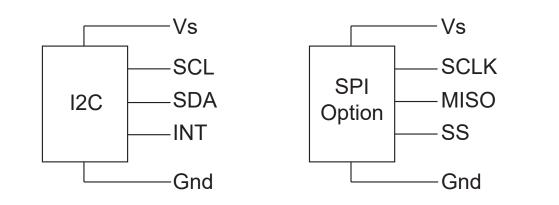
NOTE 7: TEMPERATURE OUTPUT CONVERSION FUNCTION:

Temperature (°C) =
$$Tout_{dig} \times \left(\frac{200}{2^{11}-1}\right) - 50$$

NOTE 8: A PULL-UP RESISTOR IS REQUIRED FOR CORRECT I2C USAGE. THE MINIMUM VALUE INDICATED IS FOR 5.0V OR 3.3V OPERATION.

NOTE 9: FOLLOWING SENSOR POWER-UP, THE APPLICATION MUST WAIT AT LEAST THE INDICATED TIME BEFORE ATTEMPTING TO COMMUNICATE WITH THE SENSOR.

Equivalent Circuit



Device Options

The following is a list of factory programmable options. Consult the factory to learn more about the options.

Interface

I2C and SPI interfaces are available. NOTE: SPI interface is only available with eight (8) lead packages.

Supply Voltage

Devices are characterized at either 3.3V or 5.0V depending on the options selected. It is suggested to select the option that most closely matches the application supply voltage for best possible performance.

Speed/Power

There are four options of Speed/Power. These are Fast(F), Noise Reduced(N), Low Power(L) and Sleep mode(S).

<u>Fast Mode(F)</u> Is the fastest operating mode where the device operates with continuous sampling at the fastest internal speed.

<u>Noise Reduced(N)</u>: Also operates with continuous samples however the ADC is set for over sampling for noise reduction. The conversion times are resultantly longer than the Fast(F) mode however, there is approximately 1/2 bit reduction in noise.

Low Power(L): Is similar to the Fast(F) mode with exception that the device uses an internal timer to delay between pressure conversions. The internal timer time-out triggers the next conversion cycle. The update rate is commensurately lower for this mode as a result.

<u>Sleep(S)</u>: Is similar to the Low Power(L) mode however the trigger to initiate a sample comes from the user instead of an internal timer. This is ideal for very low update rate applications that requirelow power usage. It is also ideal for synchronizing the data conversions with the host microprocessor.

Coating

Parylene coating provides a moisture barrier and protection from some harsh media. Consult factory for applicability of Parylene for the target application and sensor type. This option is not available for pressure ranges below 10 inH2O nor for J-Lead packages in any pressure range.

Soldering Recommendations

Vapor phase reflow processes are not compatible with this product.

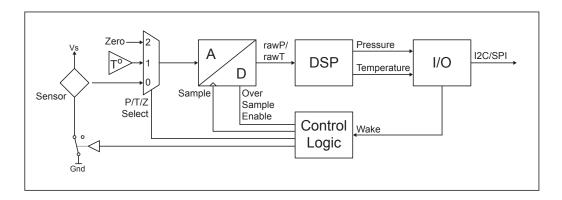
If these devices are to be subjected to solder reflow assembly or other high temperature processing, they must be baked for 1 hour at 125°C within 24 hours prior to exposure. Failure to comply may result in cracking and/or delamination of critcal interfaces within the package, and is not covered by warranty.

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Operation Overview

The DLVR is a digital sensor with a signal path that includes a sensing element, a 14 bit analog to digital converter, a DSP and an IO block that supports either an I2C or SPI interface (see Figure 1 below). The sensor also includes an internal temperature reference and associated control logic to support the configured operating mode. The sensing element is powered down while not being sampled to conserve power. Since there is a single ADC, there is also a multiplexer at the front end of the ADC that selects the signal source for the ADC.

Figure 1 - DLVR Essential Model



The ADC performs conversions on the raw sensor signal (P), the temperature reference (T) and a zero reference (Z) during an ADC zero cycle. It also has an oversampling mode for a noise reduced output. A conversion cycle that is measuring pressure is called a Normal cycle. A cycle where either a temperature measurement or zeroing is being performed is called a Special cycle.

The DSP receives the converted pressure and temperature information and applies a multi-order transfer function to compensate the pressure output. This transfer function includes compensation for span, offset, temperature effects on span, temperature effects on offset and second order temperature effects on both span and offset. There is also linearity compensation for gage devices and front to back linearity compensation for differential devices.

There are two effective operating modes of the sensor 1) Free Running and 2) Triggered. The control logic performs the synchronization of the internal functions according the factory programmed Power/Speed option (see Table 1). The Control Logic also determines the Delay between ADC samples, the regularity of the Special cycles and whether or not the ADC performs the Over Sampling. Refer to Figure 2 for the communication model associated with the operating modes listed below.

<u>Free Running Mode</u>: In the free running mode, conversion cycles are initiated internally at regular intervals. There are three options available that operate in the Free Running mode (F, N and L). Two of these (F and N) run continuously while the third option (L) has an approximate 6 ms delay between conversion cycles. All three options have Special cycles inserted at regular intervals to accomplish the ADC zeroing and temperature measurements. Two of the options utilize oversampling. Refer to Table 1 for specific option controls.

<u>Triggered Mode:</u> In the Triggered Mode, a conversion cycle is initiated by the user (or host uP). There are two available methods to wake the sensor from sleep mode. The first method (Wake All) is to wake the sensor and perform all three measurement cycles (Z, T and P). This provides completely fresh data from the sensor. The second method (Wake P) is to wake the sensor from sleep and only perform the pressure measurement (P).When using this second method, it is up to the user to interleave Wake All commands at regular intervals to ensure there is sufficiently up to date temperature information. Also, the Wake Pressure method is only available from the I2C interface (not available using a SPI interface).

Operation Overview (Cont'd)

Table 1 - DLVR Control Logic Detail

	Control Logic								
Power/ Speed Option	Power/Speed Description	Operating Mode	Over Sample	Delay Between Samples	Normal ADC Cycles	Special ADC Cycles	Special ADC Cycle Interval		
F	Fast	Бтор	No	No	1 (P)	1 (Z or T)	255		
Ν	Noise Reduced	Free Running	Yes	No	1 (P)	1 (Z or T)	255		
L	Low Power	Truining	Yes	Yes	1 (P)	1 (Z or T)	31		
s	Sleep ⁽¹⁾ (Wake Pressure)	Triggered	No	User Defined	1 (P)	n/a	Never		
3	Sleep (Wake All)	myyeleu	No	User Defined	1 (P)	2 (Z + T)	Always		

Note 1) Wake from sleep with pressure only reading is not available with SPI interface (I2C only).

Figure 2 - DLVR Communication Model

Note 1: See Table 1 for frequency of Special Cycles gered Mode - Wake All [(S)leep Option] I2C	Cycle Type	N	Normal Cycle Normal Cycle Special Cycle (1)									
ggered Mode - Wake All [(S)leep Option] I2C Wake All or SPI (SS) Read Data	Internal Operation DS	P Delay	ADC (P)	DSP	Delay	ADC (P)	DSP	Delay	ADC (P)	ADC (T or Z)	DSP	Delay ADC (P)
gered Mode - Wake All [(S)leep Option] I2C	w Data Available											
I2C Wake All Read Data Wake All Read Data	Note	1: See Table	1 for freque	ncy of Sp	ecial Cycl	les						
I2C Wake All Read Data Wake All Pl (SS) Read Data												
I2C Wake All Read Data Wake All Pl (SS) Read Data												
I2C Wake All Read Data Wake All												
or Read Data												
or SPI (SS)	ered Mode - Wake	All [(S)leep	Option]									
SPI (SS) Read Data								aad Data	Wake	All		
	12C —						R	ead Data	Wake	All		
ternal Operation Sleep ADC (Z) ADC (T) ADC (P) DSP Sleep ADC (Z) ADC (T) ADC (P) I	I2C								- Wake	All		
	I2C or SPI (SS)	Wake A					R	ead Data		_ 		
/ Data Available	I2C or SPI (SS)	Wake A		ADC	(T) AD	C (P) DSP	R	ead Data		_ 	ADC (T) ADC (P) DS
	I2C or SPI (SS)	Wake A		ADC	(T) AD	C (P) DSP	R	ead Data		_ 	ADC (T) ADC (P) DS
	I2C or SPI (SS)	Wake A		ADC	(T) AD	C (P) DSP	R	ead Data		_ 	ADC (T) ADC (P) DS
	I2C or SPI (SS) ternal Operation	Wake A		ADC	(T) AD	C (P) DSP	R	ead Data		_ 	ADC (T) ADC (P) DS
	I2C or SPI (SS)	Wake A		ADC	(T) AD	C (P) DSP	R	ead Data		_ 	ADC (T) ADC (P) DS
ggered Mode - Wake Pressure [(S)leep Option]	I2C or SPI (SS) Internal Operation lew Data Available	Wake A	ADC (Z)		(T) AD	C (P) DSP	R	ead Data		_ 	ADC (T) ADC (P) DS

Internal Operation	Sleep	ADC (P)	DSP	Sleep	ADC (P)	DSP	Sleep
New Data Available							

Digital Interface Data Format

For either type of digital interface, the format of data returned from the sensor is the same. The first 16 bits consist of the 2 Status bits followed by the 14-bit the pressure value. The third byte provides the 8 most significant bits of the measured temperature; the fourth byte provides the 3 least significant bits of temperature, followed by 5 bits of undefined filler data. With either interface, the host may terminate the transfer after receiving the first two bytes of data from the sensor, or following the third byte (if just the most-significant 8 bits of temperature are needed). Refer to Table 2 for the overall data format of the sensor. Table 3 shows the Status Bit definition.

	uipui Duiu	i oi mut			
D[31:30]	D[29:24]	D[23:16]	D[15:8]	D[7:5]	D[4:0]
S[1:0]	P[13:8]	P[7:0]	T[10:3]	T[2:0]	X[4:0]
Status	Pressure MSB	Pressure LSB	Temperature MSB	Temperature LSB	Filler bits (Undefined)

Table 2 - Output Data Format

Bit Definitions:

Status (S): Normal/command / busy / diagnostic Pressure (P): Digital pressure reading Temperature (T): Compensated temperature reading

Table 3- Status Bit Definitions

[00]	[01]	[10]	[11]
Current Data, no errors.	· /	Stale Data: Not updated since last read.	Error Condition: electrical fault or configuration invalid.

I2C Interface

I2C Communications Overview

The I2C interface uses a set of signal sequences for communication. The following is a description of the supported sequences and their associated mnemonics. Refer to Figure 3 for the associated usage of the following signal sequences.

Bus not Busy (I): During idle periods both data line (SDA) and clock line (SCL) remain HIGH.

<u>START condition (ST)</u>: A HIGH to LOW transition of SDA line while the clock (SCL) is HIGH is interpreted as START condition. START conditions are always set by the master. Each initial request for a pressure value has to begin with a START condition.

<u>Slave address (An):</u> The I C-bus requires a unique address for each device. After setting a START condition the master sends the address byte containing the 7 bit sensor address followed by a data direction bit (R/W). A "0" indicates a transmission from master to slave (WRITE), a "1" indicates a data request (READ).

<u>Acknowledge (A or N)</u>: Data is transferred in units of 8 bits (1 byte) at a time, MSB first. Each data-receiving device, whether master or slave, is required to pull the data line LOW to acknowledge receipt of the data. The Master must generate an extra clock pulse for this purpose. If the receiver does not pull the data line down, a NACK condition exists, and the slave transmitter becomes inactive. The master determines whether to send the last command again or to set the STOP condition, ending the transfer.

<u>DATA valid (Dn)</u>: State of data line represents valid data when, after a START condition, data line is stable for duration of HIGH period of clock signal. Data on line must be changed during LOW period of clock signal. There is one clock pulse per data bit.

<u>DATA operation</u>: The sensor starts to send 4 data bytes containing the current pressure and temperature values. The transmission may be halted by the host after any of the bytes by responding with a NACK.

<u>STOP condition (P)</u>: LOW to HIGH transition of the SDA line while clock (SCL) is HIGH indicates a STOP condition. STOP conditions are always generated by the master.

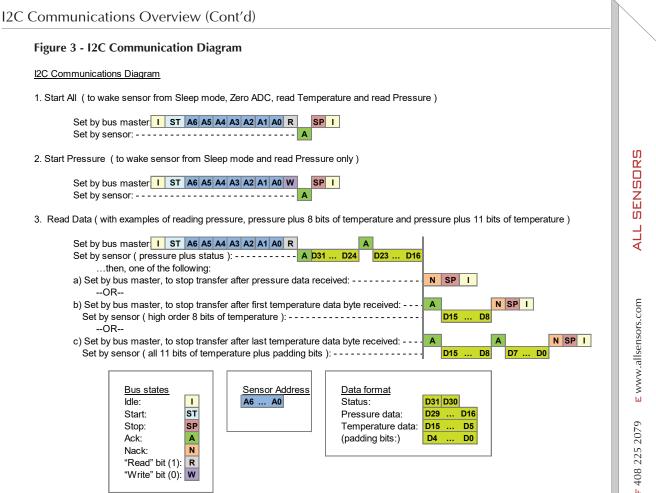


Figure 3 illustrates the sequence of signals set by both the host and the sensor for each command. Note that for the DataRead command, the host has the option of responding to the second or third bytes of data with a NACK instead of ACK. This terminates the data transmission after the pressure data, or after the pressure data and upper byte of temperature, have been transmitted. See Figure 6 for the I2C timing details.

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12C Command Sequence

Depending on whether the Fast, Noise Reduced, Low-Power, or Sleep options have been selected, the command sequence differs slightly. See Figure 3 for details of the three I2C commands.

Fast, Noise Reduced or Low-power Configuration

The part enters Free Running mode (see table 1) after power-up: it performs an initial complete measurement, writes the calculated data to the output registers, sets the INT pin high, then goes to sleep. After a delay determined by the update rate option, the part will wake up, perform measurements, update the output registers, then go back to sleep. DataRead is the only command recognized; as with the Sleep configuration, if the INT pin is ignored, the host processor can repeat this command until the Status bits indicate an updated reading.

Sleep Configuration

The part enters Triggered mode (see table 1) after power-up, and waits for a command from the bus master. If the StartAll command is received, the temperature, ADC zero, and pressure readings are all measured, and correction calculations are performed. When valid data is written to the output registers, the INT pin is set high, and the processing core goes back to sleep. The host processor then sends the DataRead command to shift out the updated values. If the INT pin is not monitored, the host can poll the output registers by repeating the DataRead command until the Status bits indicate that the values have been updated (see Tables 2 and 3). The response time depends on configuration options (refer to Table 1 and Performance Characteristics).

Depending on the application, pressure measurements may be performed by sending the StartPressure command, which only measures the pressure value and uses previously measured temperature data in calculating the compensated output value. This presents the result faster (in about 1/3 the delay time) than the StartAll command. This can be a useful method to synchronize the sensor with the host controller as well as attaining the fastest overall response time without Special cycles occuring at unwanted times. The system designer should determine the interval required for sending StartAll commands, necessary to refresh the internal temperature value and zero point data, in order to maintain accurate output values.

I2C Exceptions

1. Sending a Start condition, then a Stop condition, without any transitions on the CLK line, creates a communication error for the next communication, even if the next start condition is correct and the clock pulse is applied. A second Start condition must be set, which clears the error and allows communication to proceed.

2. The Restart condition—a falling SDA edge during data transmission when the CLK clock line is still high— creates the same stall/deadlock. In the following data request, an additional Start condition must be sent for correct communication.

3. A falling SDA edge is not allowed between the start condition and the first rising SCL edge. If using an I2C address with the first bit 0, SDA must be held low from the start condition through the first bit.

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SPI Interface

SPI Command Sequence

DLVR sensors using the SPI interface option provide 3 signals for communication: SCLK, SS (Slave Select), and MISO. This read-only signaling uses a hardware protocol to control the sensor, differing slightly with the speed/power option selected as described below:

Fast(F), Noise Reduced(N) and Low-Power(L) Configurations: After power-up, the part enters Free Running mode and begins its periodic conversion cycle, at the interval determined by the programmed Power/Speed option. This is the simplest configuration. The only bus interaction with the host is the SPI DataRead operations. Polling the sensor at a rate slower than the internal update rate will minimize bus activity and ensure that new values are presented with each transfer. Note that the Status bits should still be checked to verify updated data and the absence of error conditions.

Sleep(S) Configuration: As with the I2C option, the part enters Triggered mode after power-up, and waits for a command from the bus master. To wake the part and start a measurement cycle, the SS pin must be driven low by the host for at least 8usec, then driven high. This can be done by shifting a dummy byte of 8 bits from the sensor. This bus activity can be considered the SPI StartAll command, where the rising edge of SS is the required input to start conversion. Updated conversion data is written to the output registers after a period dependent on configuration options (see Performance Characteristics). After this update of the registers, the core goes to an inactive (sleep) state. The DataRead command simply consists of shifting out 2, 3, or 4 bytes of data from the sensor. The host can check the Status bits of the output to verify that new data has been provided. The part remains inactive following this read operation, and another StartAll operation is needed to wake the part when the next conversion is to be performed.

SPI Bit Pattern

The sequence of bits and bus signals are shown in the following illustration (Figure 4). Refer to Figure 5 in the Interface Timing Diagram section for detailed timing data. As previously described, the incoming data may be terminated by raising SS after 2, 3, or 4 bytes have been received as illustrated below.

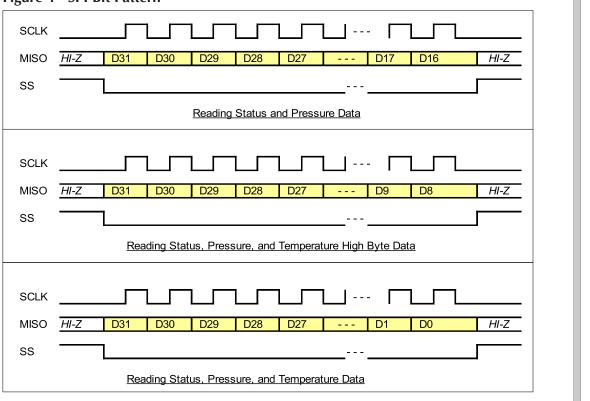


Figure 4 - SPI Bit Pattern

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Interface Timing Diagrams

Figure 5: SPI Timing Diagram

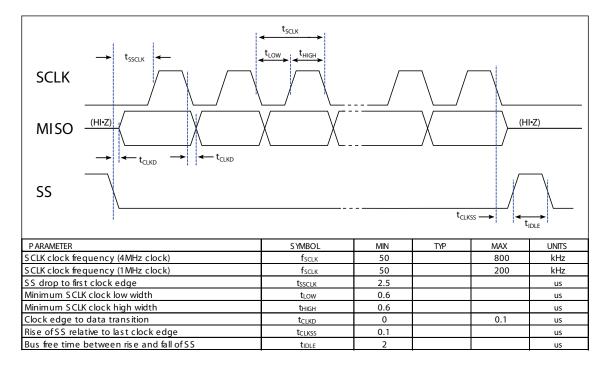
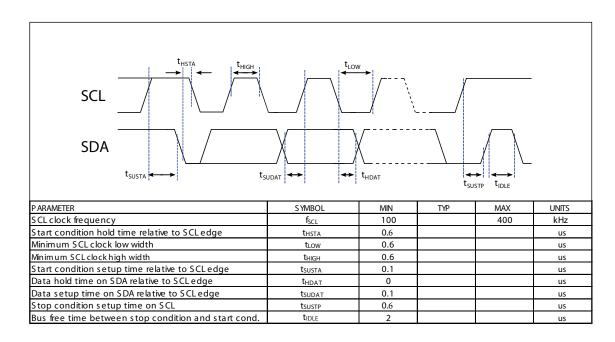


Figure 6: I2C Timing Diagram



How to Order

Refer to Table 4 for configuring a standard base part number which includes the pressure range, package and temperature range. Table 5 shows the available configuring options. The option identifier is required to complete the device part number. Refer to Table 6 for the available device package options.

Example P/N with options: DLVR-L02D-E1NS-C-NI3F

Table 4: How to configure a base part number

	SERIES	PRESS	URE RANGE						PACKAGE			Т	EMPER	RATURE RANGE
					Base Port Orientation		Lid Style			Lead Type				
	ID	ID	Description		ID	ID	Description	ID	Description	ID	Description		ID D	Description
	DLVR	F50D	±0.5 inH2O		Е	1	Dual Port Same Side	N	Non-Barbed	S	SIP (see note 10)		C C	Commercial
		L01D	±1 inH2O			2	Dual Port Opposite Side	В	Barbed	D	DIP		1 1	ndustrial
S		L02D	±2 inH2O							J	J-Lead SMT			
ATI		L05D	±5 inH2O											
ž		L10D	±10 inH2O											
6		L20D	±20 inH2O											
≦		L30D	±30 inH2O											
ORDERING INFORMATION		L60D	±60 inH2O											
DEH		L01G	0 to 1 inH2O											
ы В		L02G	0 to 2 inH2O											
_		L05G	0 to 5 inH2O											
		L10G	0 to 10 inH2O											
		L20G	0 to 20 inH2O											
		L30G	0 to 30 inH2O											
		L60G	0 to 60 inH2O											
Example	DLVR	L02D		-	E	1		Ν		S		-[с	

Table 5: How to configure an option identifier

	COATING			INTERFACE	SL	JPPLY VOLTAGE	SPEED/POWER		
NO	ID	Description	ID	Description	ID	Description	ID	Description	
ATI	Ν	No Coating	Ι	I2C, address 0x28	3	3.3V	F	Fast	
INFORMATION	Р	Parylene Coating ⁸	S	SPI (see note 10)	5	5.0V	Ν	Noise reduced	
LFO			3	I2C, address 0x38			L	Low Power	
			4	I2C, address 0x48			S	Sleep Mode	
ORDERING			5	I2C, address 0x58					
DEF			6	I2C, address 0x68					
OR			7	I2C, address 0x78					
			9	I2C, address 0x29					
Example	Ν		1		3		F		

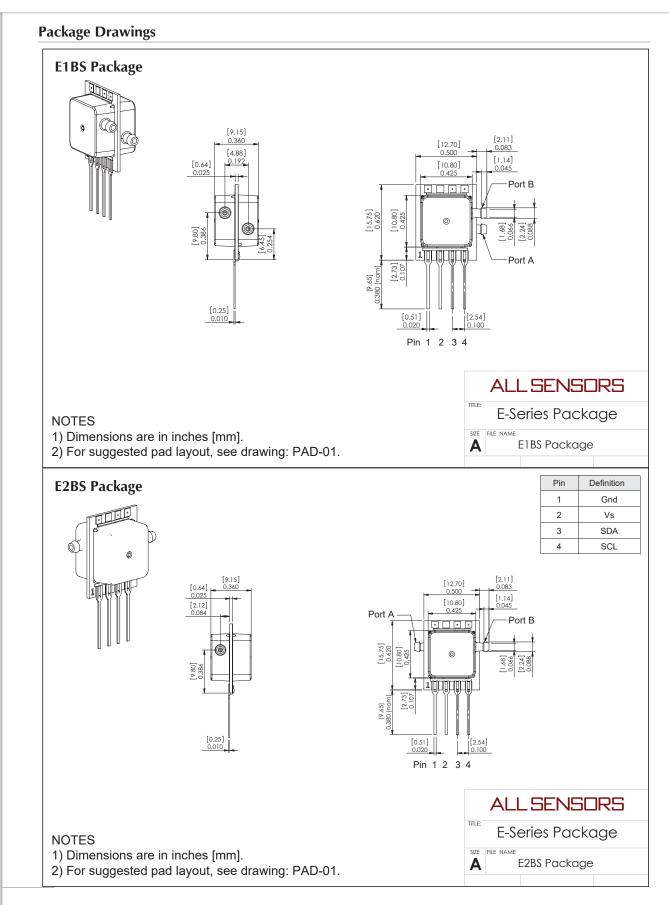
Table 6: Available E-Series Package Configurations

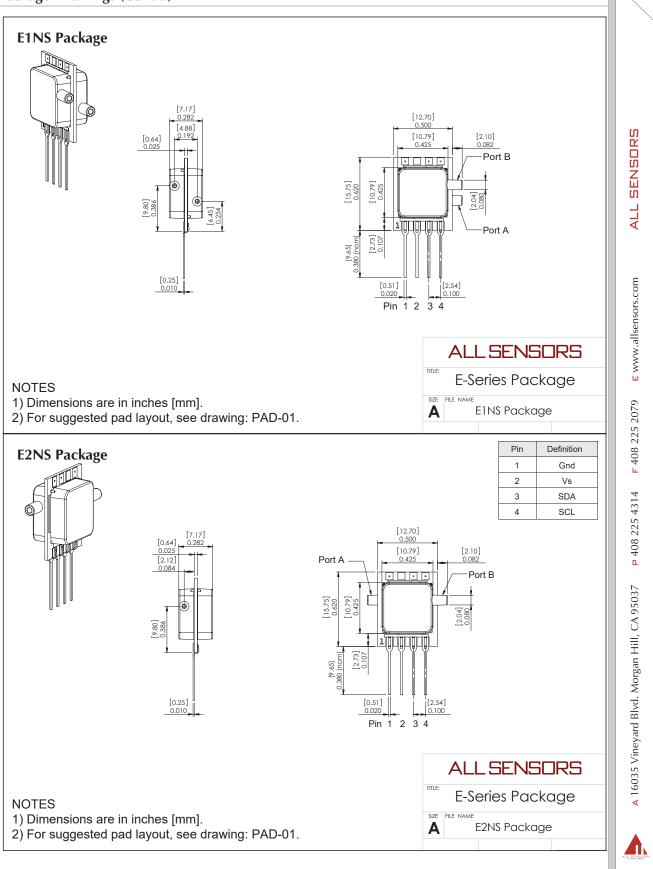
Port		Non-Ba			Barbed Lid						
Orientation		Lead	Style		Lead Style						
Onentation	SIP	DIP	J Lead SMT	Low Profile DIP	SIP	DIP	J Lead SMT	Low Profile DIP			
Dual Port Same Side				N/A			N/A	N/A			
	E1NS	E1ND	E1NJ		E1BS	E1BD					
Dual Port Opposite Side				N/A			N/A	N/A			
	E2NS	E2ND	E2NJ		E2BS	E2BD					
Single Port (Gage)	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A			

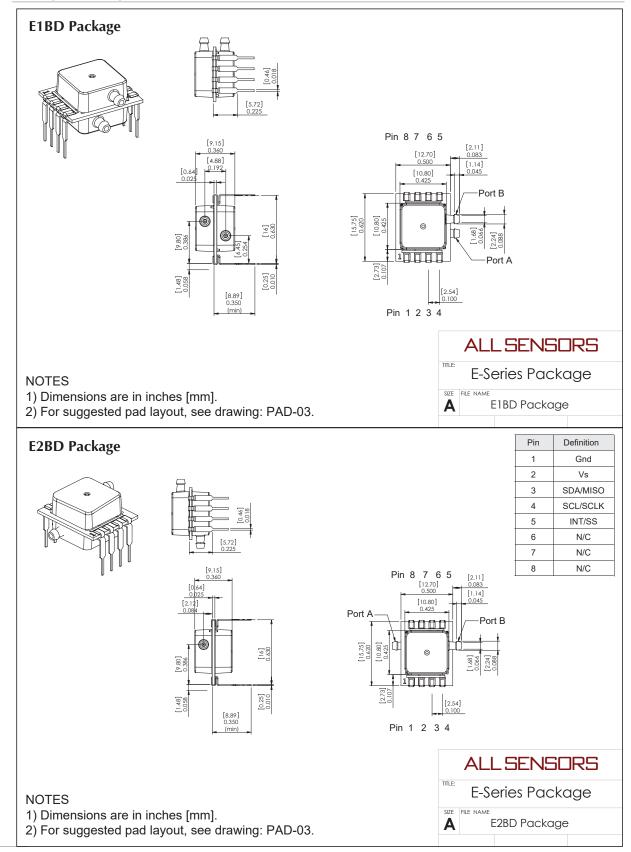
Specification Notes (Cont'd.)

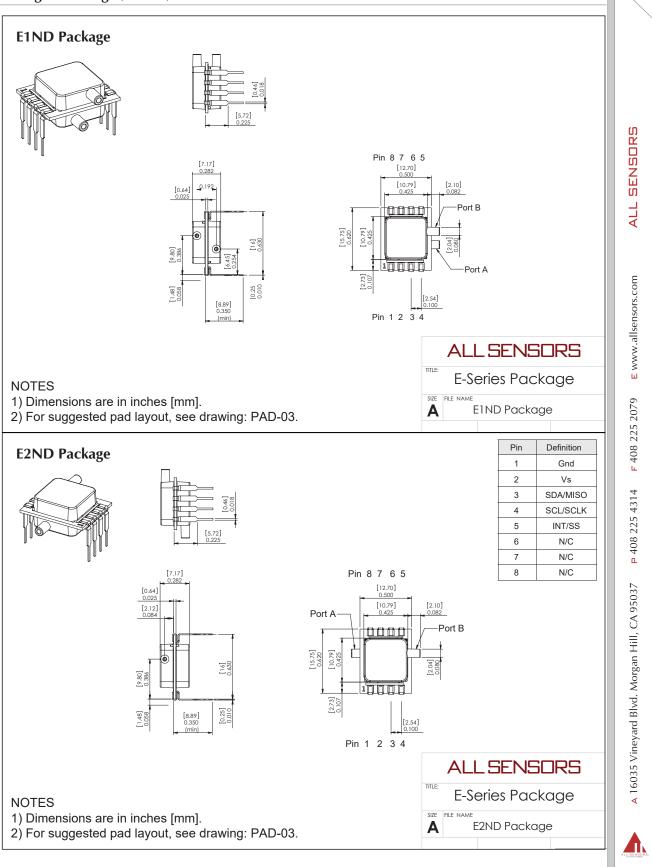
NOTE 10: PARYLENE COATING NOT OFFERED IN J-LEAD SMT CONFIGURATION. Note 11: SPI INTERFACE IS ONLY AVAILABLE IN 8-LEAD DIP PACKAGES.

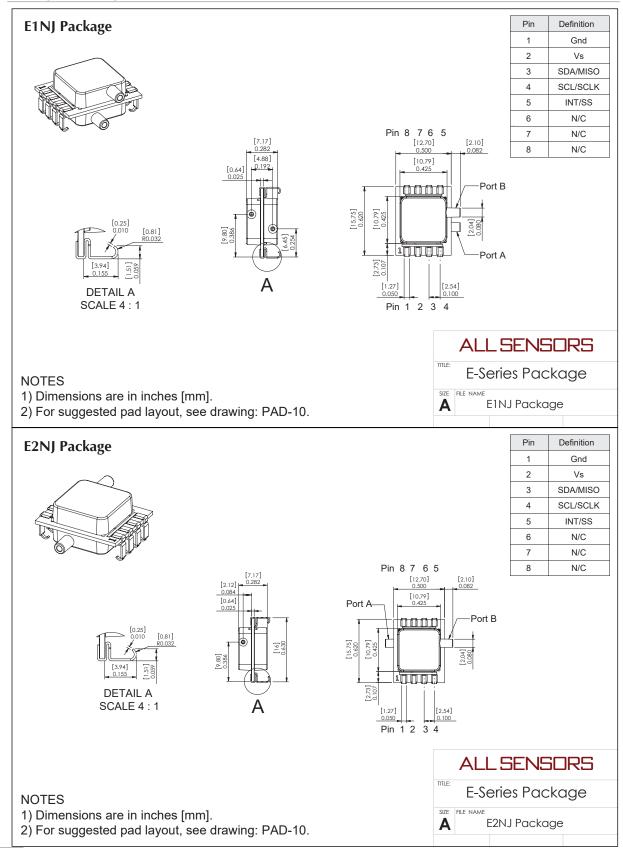
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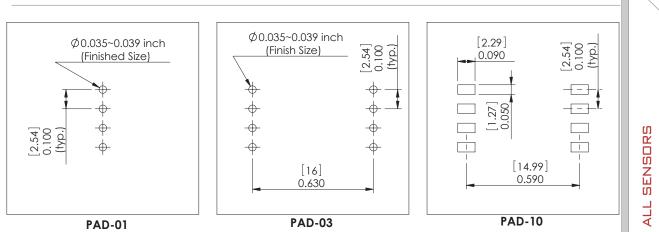




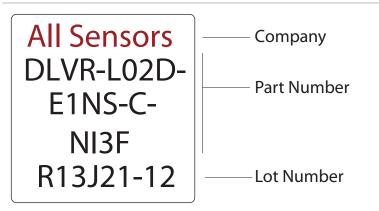




Suggested Pad Layouts



Product Labeling



Example Device Label

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